Toshiba Bi-CD Integrated Circuit Silicon Monolithic

TB6612FNG

Driver IC for Dual DC motor

TB6612FNG is a driver IC for DC motor with output transistor in LD MOS structure with low ON-resistor. Two input signals, IN1 and IN2, can choose one of four modes such as CW, CCW, short brake, and stop mode.

SSOP24-P-300-0.65A

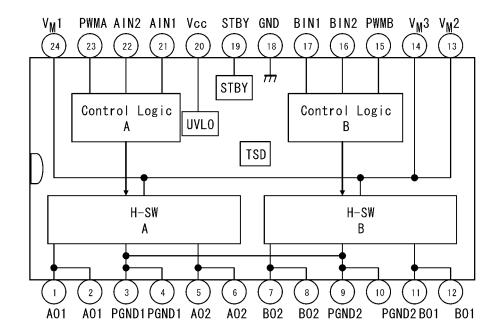
Weight: 0.14 g (typ.)

Features

- Power supply voltage: VM = 15 V(Max)
- Output current: IOUT = 1.2 A(ave)/3.2 A (peak)
- Output low ON resistor: 0.5Ω (upper+lower Typ. @ VM ≥ 5 V)
- Standby (Power save) system
- CW/CCW/short brake/stop function modes
- · Built-in thermal shutdown circuit and low voltage detecting circuit
- Small faced package(SSOP24: 0.65 mm Lead pitch)

* This product has a MOS structure and is sensitive to electrostatic discharge. When handling this product, ensure that the environment is protected against electrostatic discharge by using an earth strap, a conductive mat and an ionizer. Ensure also that the ambient temperature and relative humidity are maintained at reasonable levels.

Block Diagram



Pin Functions

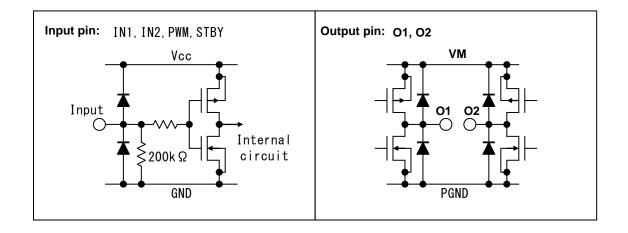
No.	Pin Name	I/O	Function					
1	AO1		ch A output 1					
2	AO1	0	ch A output 1					
3	PGND1		Power GND 1					
4	PGND1	_	YOWER GIND T					
5	AO2	0	ch A output 2					
6	AO2	O	ch A output 2					
7	BO2	0	ch B output 2					
8	BO2	Ü						
9	PGND2		Power GND 2					
10	PGND2		LOMBI GIAD 5					
11	BO1	0	ch B output 1					
12	BO1	Ŭ	στο σαίραι τ					
13	VM2		Motor supply					
14	VM3		ινιοιοι συρριγ					
15	PWMB	I	ch B PWM input/200 kΩ pull-down at internal					
16	BIN2	- 1	ch B input 2/200 kΩ pull-down at internal					
17	BIN1	I	ch B input 1/200 kΩ pull-down at internal					
18	GND	_	Small signal GND					
19	STBY	I	"L" = standby/200 kΩ pull-down at internal					
20	Vcc	_	Small signal supply					
21	AIN1	I	ch A input 1/200 kΩ pull-down at internal					
22	AIN2	I	ch A input 2/200 kΩ pull-down at internal					
23	PWMA	I	ch A PWM input/200 kΩ pull-down at internal					
24	VM1	_	Motor supply					

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	Remarks
Complexedtere	VM	15	V	
Supply voltage	Vcc	6		
Input voltage	V _{IN}	-0.2 to 6	V	IN1,IN2,STBY,PWM pins
Output voltage	Output voltage VouT		V	O1,O2 pins
	lout	1.2		Per 1 ch
Output current	I _{OUT} (peak)	2	А	tw = 20 ms Continuous pulse, Duty ≤ 20%
		3.2		tw = 10 ms Single pulse
	P _D	0.78	W	IC only
Power dissipation		0.89		50 mm × 50 mm t = 1.6 mm Cu ≥ 40% in PCB mounting
i ower dissipation		1.36		76.2 mm × 114.3 mm $t = 1.6$ mm Cu $\ge 30\%$ in PCB mounting
Operating temperature	T _{opr}	-20 to 85	°C	
Storage temperature	T _{stg}	-55 to 150	°C	

Operating Range (Ta = -20 to 85°C)

Characteristics	Symbol	Min	Тур.	Max	Unit	Remarks
Cumply voltogo	Vcc	2.7	3	5.5	V	
Supply voltage	VM	2.5	5	13.5	V	
	lout	1	1	1.0		VM ≥ 4.5 V
Output current (H-SW)				0.4	Α	4.5 V > VM ≥ 2.5 V Without PWM Operation
Switching frequency	fpwm	-	-	100	kHz	

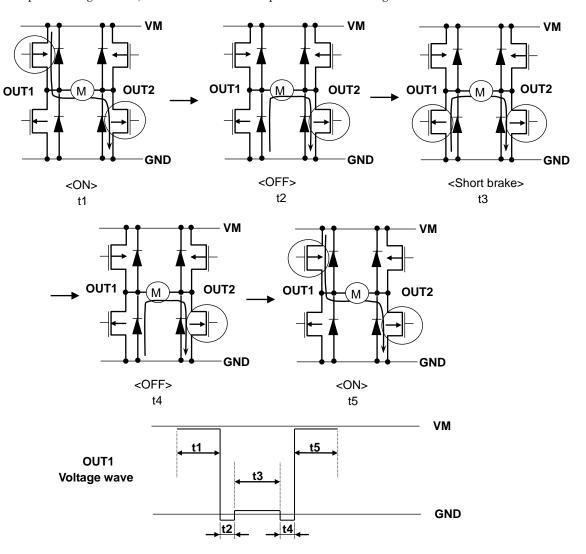


H-SW Control Function

Input				Output				
IN1	IN2	PWM	STBY	OUT1	OUT2	Mode		
н	Н	H/L	Н	L	L	Short brake		
L H	Н		Н	L	Н	CCW		
	П	L H		L	L	Short brake		
Н	L	L	Н	Н	Н	L	CW	
			L	Н	L	L	Short brake	
L	L	H	Ħ	OFF (High impedance)		Stop		
H/L	H/L	H/L	L	OFF (High impedance)		Standby		

H-SW Operating Description

• To prevent penetrating current, dead time t2 and t4 is provided in switching to each mode in the IC.



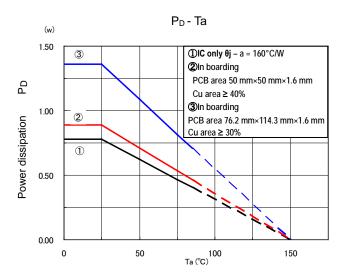


Electrical Characteristics (unless otherwise specified, Ta = 25°C, Vcc = 3 V, VM = 5 V)

Characteristics	Symbol		Test Condition	Min	Тур.	Max	Unit	
	Icc(3 V)		STBY = Vcc = 3 V, VM = 5 V	_	1.1	1.8	mA	
0	Icc(5.5 V)		STBY = Vcc = 5.5 V, VM = 5 V	_	1.5	2.2		
Supply current	ICC(STB)		CTDV 0.V	_	1	1	μΑ	
			STBY = 0 V	_	1	1		
Control inner treate no	V _I H V _I L			Vcc×0.7	1	Vcc+0.2	٧	
Control input voltage			_	-0.2	_	Vcc×0.3		
Ocataclian of comment	IIH		V _{IN} = 3 V	5	15	25		
Control input current	I	L	V _{IN} = 0 V	_	_	1	μΑ	
Otana illa sa baranta and tana kanana	V _{IH} (STB) V _{IL} (STB)			Vcc×0.7	_	Vcc+0.2	V	
Standby input voltage			_	-0.2	_	Vcc×0.3		
Otana dia dia manta adamana	l _{IH(}	STB)	V _{IN} = 3 V	5	15	25		
Standby input current	I _{IL(STB)}		V _{IN} = 0 V	_	_	1 μΑ		
Output saturating voltage	V _{sat(U+L)1}		I _O = 1 A, Vcc = VM = 5 V		0.7	V		
Output saturating voltage			$I_O = 0.3 \text{ A}, \text{ Vcc} = \text{ VM} = 5 \text{ V}$	c = VM = 5 V — 0.15 0.2		0.21	v	
Output lookage current	I _{L(U)}		VM = V _{OUT} = 15 V — — —		1	۸		
Output leakage current	I _{L(L)}		VM = 15 V, V _{OUT} = 0 V		_	_	μΑ	
Dogoporative diade \/C	V _{F(U)}		I- 1A	_	1	1.1	V	
Regenerative diode VF			I _F = 1A	_	1	1.1		
Low voltage detecting voltage	UVLD		(Design target only)	_	1.9			
Recovering voltage	UVLC			_	2.2	_		
	t _r		(Danisa tanan tank)	_	24	_		
Dannana anaad			(Design target only)	_	41	_		
Response speed	Dead	H to L	Penetration protect time		50		ns	
	time	L to H	(Design target only)	_	230	_		
Thermal shutdown circuit operating temperature	ng temperature TSD nal shutdown		(Design target only)		175		°C	
Thermal shutdown hysteresis			(Design target only)	_	20	_		

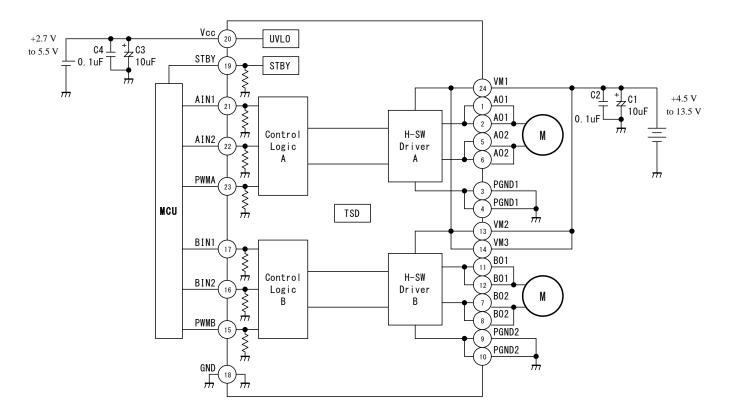


Target characteristics





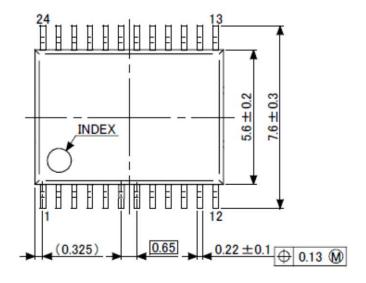
Typical Application Diagram



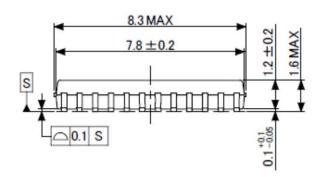
Note: Condensers for noise absorption (C1, C2, C3, and C4) should be connected as close as possible to the IC.

Package Dimennsions

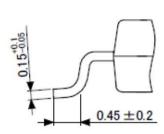
SSOP24-P-300-0.65A "Unit: mm"







Detail of a terminal



Weght: 0.14 g (typ)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations Notes on handling of ICs

- [1] The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.

 Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- [2] Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- [3] If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
 - Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- [4] Do not insert devices in the wrong orientation or incorrectly.
 - Make sure that the positive and negative terminals of power supplies are connected properly.
 - Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
 - In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

Points to remember on handling of ICs

(1) Thermal Shutdown Circuit

Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately.

Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.

(2) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(3) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.



RESTRICTIONS ON PRODUCT USE

- Toshiba Corporation, and its subsidiaries and affiliates (collectively "TOSHIBA"), reserve the right to make changes to the information in this document, and related hardware, software and systems (collectively "Product") without notice.
- This document and any information herein may not be reproduced without prior written permission from TOSHIBA. Even with TOSHIBA's written permission, reproduction is permissible only if reproduction is without alteration/omission.
- Though TOSHIBA works continually to improve Product's quality and reliability, Product can malfunction or fail. Customers are responsible for complying with safety standards and for providing adequate designs and safeguards for their hardware, software and systems which minimize risk and avoid situations in which a malfunction or failure of Product could cause loss of human life, bodily injury or damage to property, including data loss or corruption. Before customers use the Product, create designs including the Product, or incorporate the Product into their own applications, customers must also refer to and comply with (a) the latest versions of all relevant TOSHIBA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the "TOSHIBA Semiconductor Reliability Handbook" and (b) the instructions for the application with which the Product will be used with or for. Customers are solely responsible for all aspects of their own product design or applications, including but not limited to (a) determining the appropriateness of the use of this Product in such design or applications; (b) evaluating and determining the applicability of any information contained in this document, or in charts, diagrams, programs, algorithms, sample application circuits, or any other referenced documents; and (c) validating all operating parameters for such designs and applications. TOSHIBA ASSUMES NO LIABILITY FOR CUSTOMERS' PRODUCT DESIGN OR APPLICATIONS.
- PRODUCT IS NEITHER INTENDED NOR WARRANTED FOR USE IN EQUIPMENTS OR SYSTEMS THAT REQUIRE
 EXTRAORDINARILY HIGH LEVELS OF QUALITY AND/OR RELIABILITY, AND/OR A MALFUNCTION OR FAILURE OF WHICH
 MAY CAUSE LOSS OF HUMAN LIFE, BODILY INJURY, SERIOUS PROPERTY DAMAGE AND/OR SERIOUS PUBLIC IMPACT
 ("UNINTENDED USE"). Except for specific applications as expressly stated in this document, Unintended Use includes, without
 limitation, equipment used in nuclear facilities, equipment used in the aerospace industry, medical equipment, equipment used for
 automobiles, trains, ships and other transportation, traffic signaling equipment, equipment used to control combustions or explosions,
 safety devices, elevators and escalators, devices related to electric power, and equipment used in finance-related fields. IF YOU USE
 PRODUCT FOR UNINTENDED USE, TOSHIBA ASSUMES NO LIABILITY FOR PRODUCT. For details, please contact your
 TOSHIBA sales representative.
- · Do not disassemble, analyze, reverse-engineer, alter, modify, translate or copy Product, whether in whole or in part.
- Product shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any
 applicable laws or regulations.
- The information contained herein is presented only as guidance for Product use. No responsibility is assumed by TOSHIBA for any infringement of patents or any other intellectual property rights of third parties that may result from the use of Product. No license to any intellectual property right is granted by this document, whether express or implied, by estoppel or otherwise.
- ABSENT A WRITTEN SIGNED AGREEMENT, EXCEPT AS PROVIDED IN THE RELEVANT TERMS AND CONDITIONS OF SALE
 FOR PRODUCT, AND TO THE MAXIMUM EXTENT ALLOWABLE BY LAW, TOSHIBA (1) ASSUMES NO LIABILITY
 WHATSOEVER, INCLUDING WITHOUT LIMITATION, INDIRECT, CONSEQUENTIAL, SPECIAL, OR INCIDENTAL DAMAGES OR
 LOSS, INCLUDING WITHOUT LIMITATION, LOSS OF PROFITS, LOSS OF OPPORTUNITIES, BUSINESS INTERRUPTION AND
 LOSS OF DATA, AND (2) DISCLAIMS ANY AND ALL EXPRESS OR IMPLIED WARRANTIES AND CONDITIONS RELATED TO
 SALE, USE OF PRODUCT, OR INFORMATION, INCLUDING WARRANTIES OR CONDITIONS OF MERCHANTABILITY, FITNESS
 FOR A PARTICULAR PURPOSE, ACCURACY OF INFORMATION, OR NONINFRINGEMENT.
- Do not use or otherwise make available Product or related software or technology for any military purposes, including without limitation, for the design, development, use, stockpiling or manufacturing of nuclear, chemical, or biological weapons or missile technology products (mass destruction weapons). Product and related software and technology may be controlled under the applicable export laws and regulations including, without limitation, the Japanese Foreign Exchange and Foreign Trade Law and the U.S. Export Administration Regulations. Export and re-export of Product or related software or technology are strictly prohibited except in compliance with all applicable export laws and regulations.
- Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
 Please use Product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. TOSHIBA ASSUMES NO LIABILITY FOR DAMAGES OR LOSSES
 OCCURRING AS A RESULT OF NONCOMPLIANCE WITH APPLICABLE LAWS AND REGULATIONS.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: <u>org@eplast1.ru</u>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.